

Semiconductor test center for chips and sensors in Penang, Malaysia

August 2023

General information

With its semiconductor test center in Penang, opened in August 2023, Bosch is creating additional capacity within its worldwide manufacturing network to meet the continued high demand for automotive chips and sensors. It brings Bosch closer to packaging companies (so called OSATs) in the region and to customers in the important Asian market.

Total investment:	2023: 65 million euros; Planned investment of a further 285 million euros by the middle of the next decade.
Site:	100.000 m ² thereof 18.000 m ² including clean rooms, office space and R&D labs.
Clean room are final test:	3,000 m ² ; additional 3,000 m ² are currently in construction and will be available until the end of 2023.
Construction timeline:	Groundbreaking: 05/2021 First production run: 01/2023 (ASIC) Opening: 08/2023 Ramp up production: 08/2023.

Associates:	By the middle of the next decade, the semiconductor backend center will grow up to 400 associates.
Backend tasks:	Chips are separated from the wafers, assembled and tested.
Manufactured products:	Application-specific integrated circuits (ASICs), MEMS sensors.
Served applications:	Electronic control units for safety systems and driver assistance systems such as airbag, Electronic Stability Control (ESC) or parking assistants; Electronic control units for electric and IC powertrain.